

OPA2604

www.burr-brown.com/databook/OPA2604.html

# Dual FET-Input, Low Distortion OPERATIONAL AMPLIFIER

## FEATURES

- LOW DISTORTION: 0.0003% at 1kHz
- LOW NOISE:  $10\text{nV}/\sqrt{\text{Hz}}$
- HIGH SLEW RATE:  $25\text{V}/\mu\text{s}$
- WIDE GAIN-BANDWIDTH: 20MHz
- UNITY-GAIN STABLE
- WIDE SUPPLY RANGE:  $V_s = \pm 4.5$  to  $\pm 24\text{V}$
- DRIVES  $600\Omega$  LOADS

## APPLICATIONS

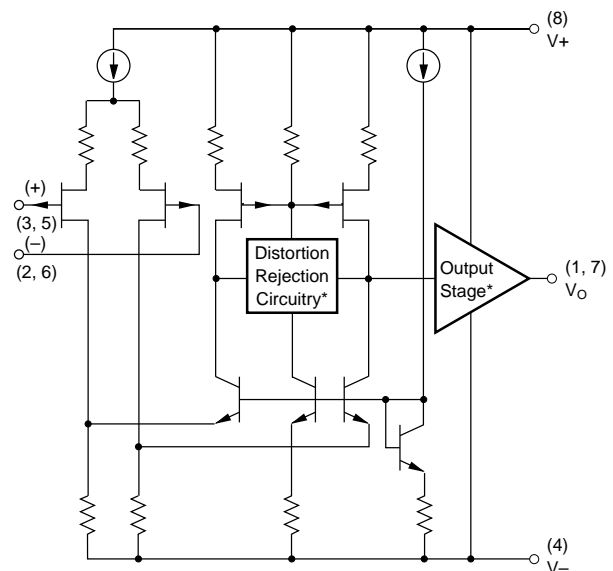
- PROFESSIONAL AUDIO EQUIPMENT
- PCM DAC I/V CONVERTER
- SPECTRAL ANALYSIS EQUIPMENT
- ACTIVE FILTERS
- TRANSDUCER AMPLIFIER
- DATA ACQUISITION

## DESCRIPTION

The OPA2604 is a dual, FET-input operational amplifier designed for enhanced AC performance. Very low distortion, low noise and wide bandwidth provide superior performance in high quality audio and other applications requiring excellent dynamic performance.

New circuit techniques and special laser trimming of dynamic circuit performance yield very low harmonic distortion. The result is an op amp with exceptional sound quality. The low-noise FET input of the OPA2604 provides wide dynamic range, even with high source impedance. Offset voltage is laser-trimmed to minimize the need for interstage coupling capacitors.

The OPA2604 is available in 8-pin plastic mini-DIP and SO-8 surface-mount packages, specified for the  $-25^\circ\text{C}$  to  $+85^\circ\text{C}$  temperature range.



\* Patents Granted:  
#5053718, 5019789

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Internet: <http://www.burr-brown.com/> • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

# SPECIFICATIONS

## ELECTRICAL

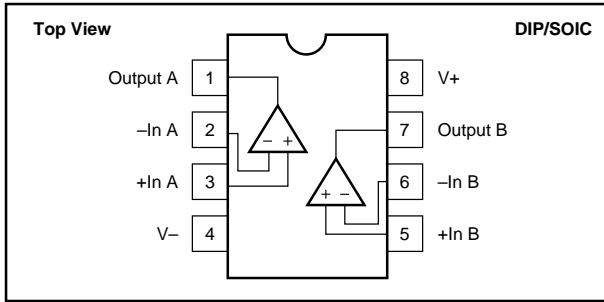
At  $T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$ , unless otherwise noted.

PARAMETER	CONDITION	OPA2604AP, AU			UNITS
		MIN	TYP	MAX	
<b>OFFSET VOLTAGE</b> Input Offset Voltage Average Drift Power Supply Rejection	$V_S = \pm 5 \text{ to } \pm 24\text{V}$	70	$\pm 1$ $\pm 8$ 80	$\pm 5$	mV $\mu\text{V}/^\circ\text{C}$ dB
<b>INPUT BIAS CURRENT<sup>(1)</sup></b> Input Bias Current Input Offset Current	$V_{CM} = 0\text{V}$ $V_{CM} = 0\text{V}$		100 $\pm 4$		pA pA
<b>NOISE</b> Input Voltage Noise Noise Density: $f = 10\text{Hz}$ $f = 100\text{Hz}$ $f = 1\text{kHz}$ $f = 10\text{kHz}$ Voltage Noise, BW = 20Hz to 20kHz Input Bias Current Noise Current Noise Density, $f = 0.1\text{Hz}$ to 20kHz			25 15 11 10 1.5 6		$\text{nV}/\sqrt{\text{Hz}}$ $\text{nV}/\sqrt{\text{Hz}}$ $\text{nV}/\sqrt{\text{Hz}}$ $\text{nV}/\sqrt{\text{Hz}}$ $\mu\text{Vp-p}$ $\text{fA}/\sqrt{\text{Hz}}$
<b>INPUT VOLTAGE RANGE</b> Common-Mode Input Range Common-Mode Rejection	$V_{CM} = \pm 12\text{V}$	$\pm 12$ 80	$\pm 13$ 100		V dB
<b>INPUT IMPEDANCE</b> Differential Common-Mode			$10^{12} \parallel 8$ $10^{12} \parallel 10$		$\Omega \parallel \text{pF}$ $\Omega \parallel \text{pF}$
<b>OPEN-LOOP GAIN</b> Open-Loop Voltage Gain	$V_O = \pm 10\text{V}$ , $R_L = 1\text{k}\Omega$	80	100		dB
<b>FREQUENCY RESPONSE</b> Gain-Bandwidth Product Slew Rate Settling Time: 0.01% 0.1% Total Harmonic Distortion + Noise (THD+N) Channel Separation	$G = 100$ $20\text{Vp-p}$ , $R_L = 1\text{k}\Omega$ $G = -1$ , 10V Step  $G = 1$ , $f = 1\text{kHz}$ $V_O = 3.5\text{Vrms}$ , $R_L = 1\text{k}\Omega$ $f = 1\text{kHz}$ , $R_L = 1\text{k}\Omega$	15	20 25 1.5 1 0.0003 142		MHz $\text{V}/\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$ % dB
<b>OUTPUT</b> Voltage Output Current Output Short Circuit Current Output Resistance, Open-Loop	$R_L = 600\Omega$ $V_O = \pm 12\text{V}$	$\pm 11$	$\pm 12$ $\pm 35$ $\pm 40$ 25		V mA mA $\Omega$
<b>POWER SUPPLY</b> Specified Operating Voltage Operating Voltage Range Current, Total Both Amplifiers	$I_O = 0$	$\pm 4.5$	$\pm 15$ $\pm 10.5$	$\pm 24$ $\pm 12$	V V mA
<b>TEMPERATURE RANGE</b> Specification Storage Thermal Resistance <sup>(2)</sup> , $\theta_{JA}$		-25 -40		+85 +125	$^\circ\text{C}$ $^\circ\text{C}$ $^\circ\text{C}/\text{W}$

NOTES: (1) Typical performance, measured fully warmed-up. (2) Soldered to circuit board—see text.

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## PIN CONFIGURATION



## ELECTROSTATIC DISCHARGE SENSITIVITY

Any integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet published specifications.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Power Supply Voltage .....	±25V
Input Voltage .....	(V-) -1V to (V+) +1V
Output Short Circuit to Ground .....	Continuous
Operating Temperature .....	-40°C to +100°C
Storage Temperature .....	-40°C to +125°C
Junction Temperature .....	+150°C
Lead Temperature (soldering, 10s) AP .....	+300°C
Lead Temperature (soldering, 3s) AU .....	+260°C

NOTE: (1) Stresses above these ratings may cause permanent damage.

## ORDERING INFORMATION

PRODUCT	PACKAGE	TEMP. RANGE
OPA2604AP	8-Pin Plastic DIP	-25°C to +85°C
OPA2604AU	SO-8 Surface-Mount	-25°C to +85°C

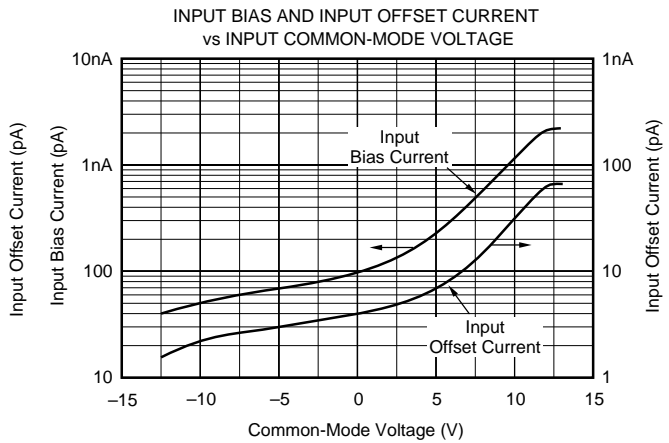
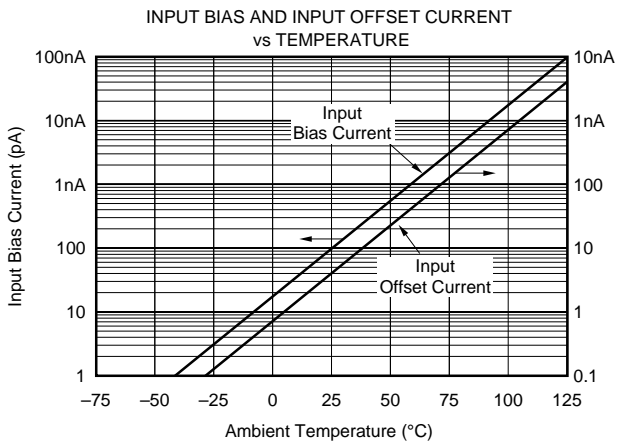
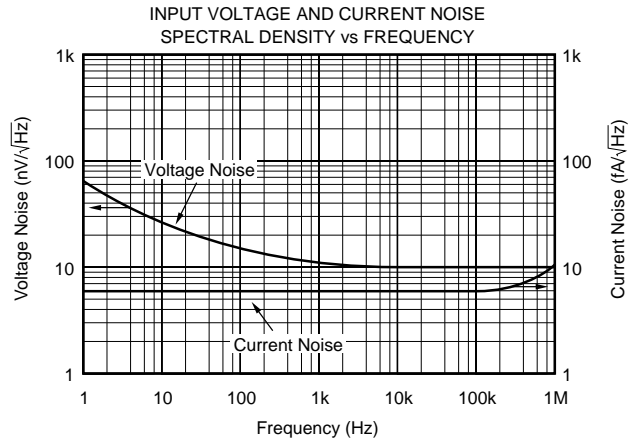
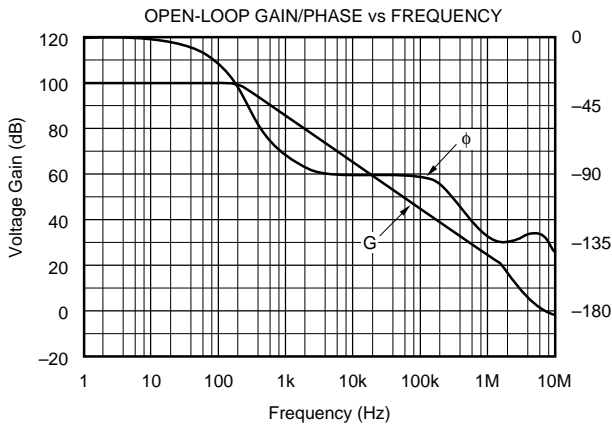
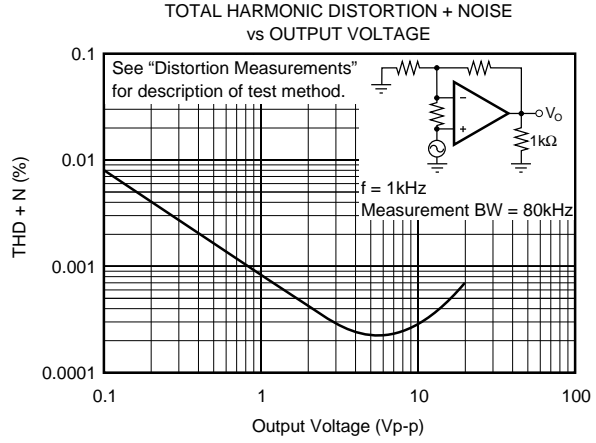
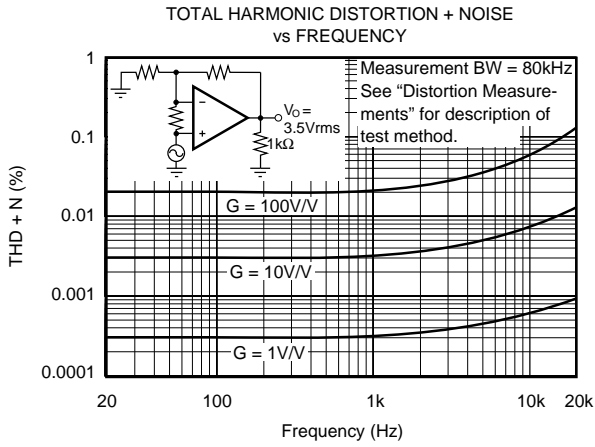
## PACKAGING INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER <sup>(1)</sup>
OPA2604AP	8-Pin Plastic DIP	006
OPA2604AU	SO-8 Surface-Mount	182

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

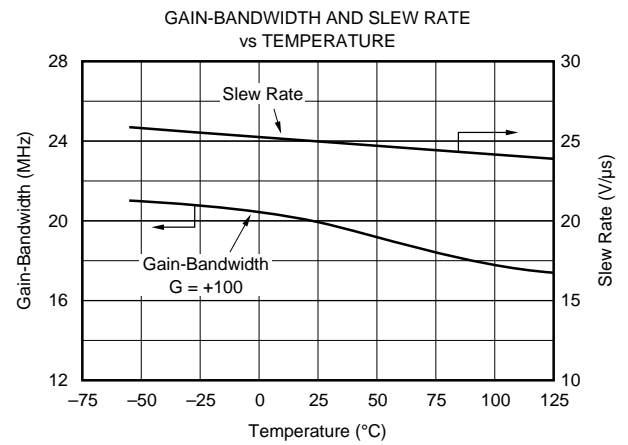
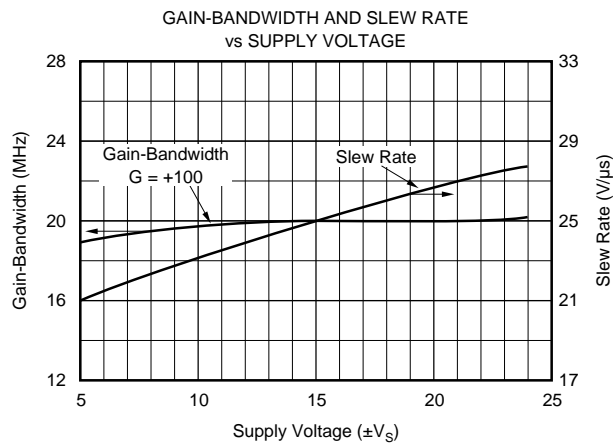
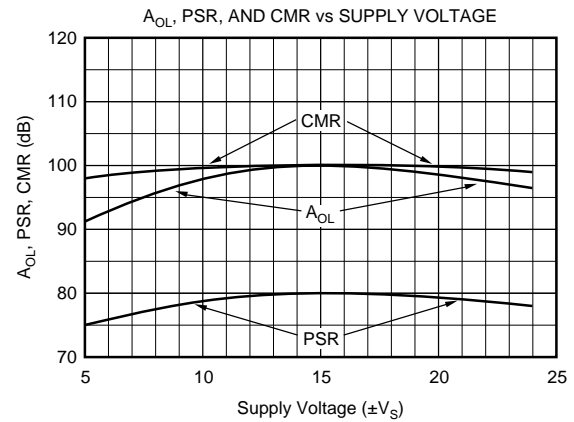
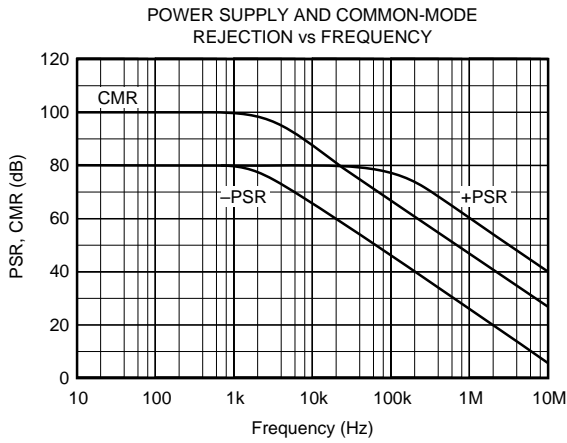
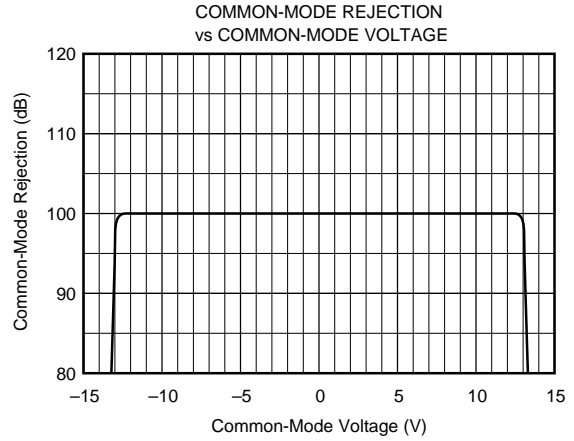
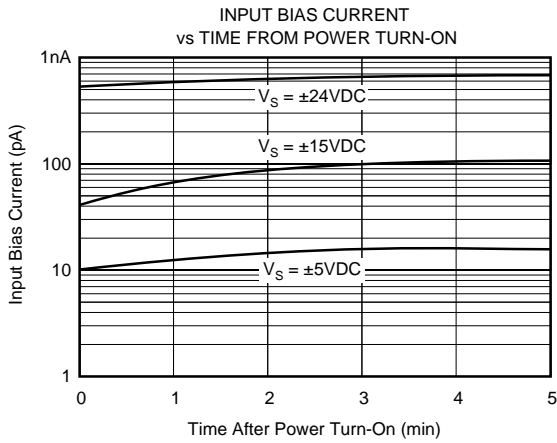
# TYPICAL PERFORMANCE CURVES

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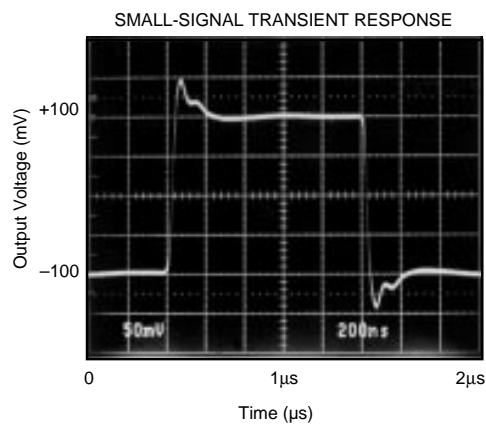
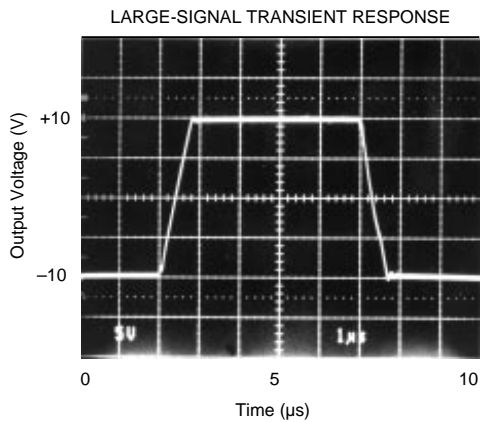
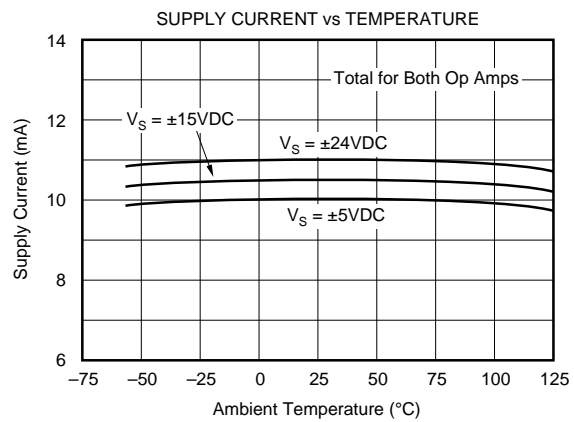
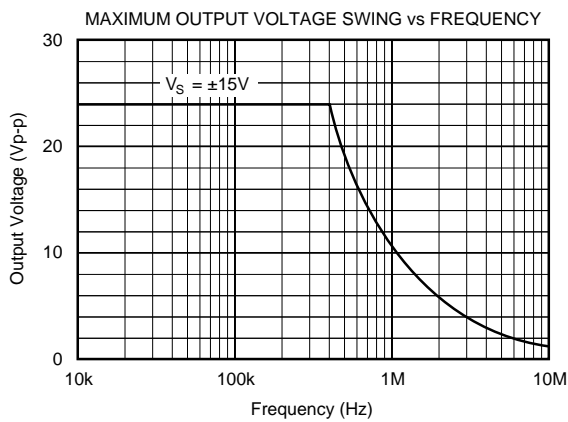
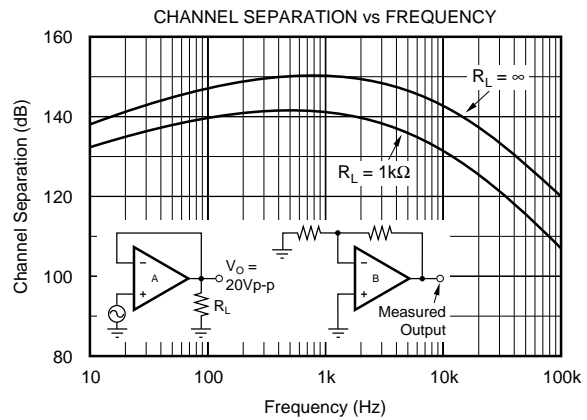
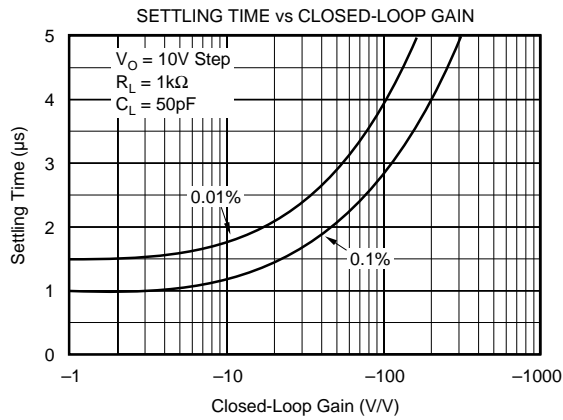
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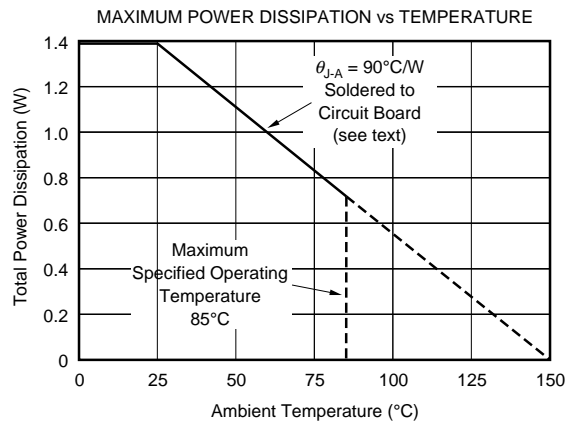
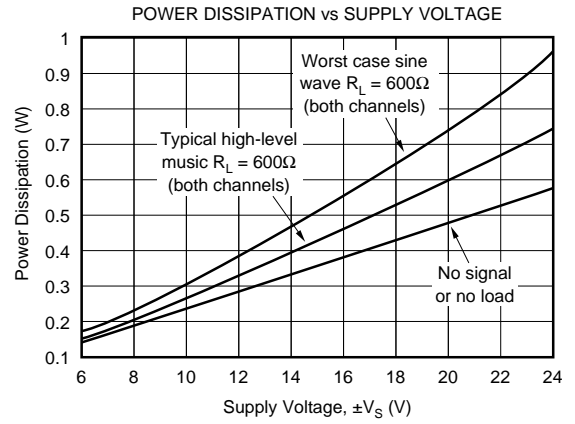
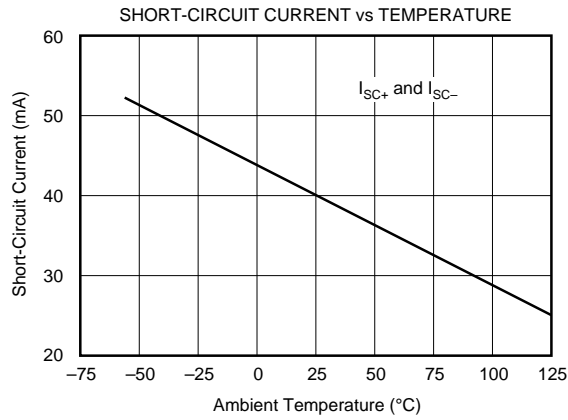
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# TYPICAL PERFORMANCE CURVES (CONT)

At  $T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$ , unless otherwise noted.



# APPLICATIONS INFORMATION

The OPA2604 is unity-gain stable, making it easy to use in a wide range of circuitry. Applications with noisy or high impedance power supply lines may require decoupling capacitors close to the device pins. In most cases 1 $\mu$ F tantalum capacitors are adequate.

## DISTORTION MEASUREMENTS

The distortion produced by the OPA2604 is below the measurement limit of virtually all commercially available equipment. A special test circuit, however, can be used to extend the measurement capabilities.

Op amp distortion can be considered an internal error source which can be referred to the input. Figure 1 shows a circuit which causes the op amp distortion to be 101 times greater than normally produced by the op amp. The addition of  $R_3$  to the otherwise standard non-inverting amplifier configuration alters the feedback factor or noise gain of the circuit. The closed-loop gain is unchanged, but the feedback available for error correction is reduced by a factor of 101. This extends the measurement limit, including the effects of the signal-source purity, by a factor of 101. Note that the input signal and load applied to the op amp are the same as with conventional feedback without  $R_3$ .

Validity of this technique can be verified by duplicating measurements at high gain and/or high frequency where the distortion is within the measurement capability of the test equipment. Measurements for this data sheet were made with the Audio Precision System One which greatly simplifies such repetitive measurements. The measurement technique can, however, be performed with manual distortion measurement instruments.

## CAPACITIVE LOADS

The dynamic characteristics of the OPA2604 have been optimized for commonly encountered gains, loads and operating conditions. The combination of low closed-loop gain

and capacitive load will decrease the phase margin and may lead to gain peaking or oscillations. Load capacitance reacts with the op amp's open-loop output resistance to form an additional pole in the feedback loop. Figure 2 shows various circuits which preserve phase margin with capacitive load. Request Application Bulletin AB-028 for details of analysis techniques and applications circuits.

For the unity-gain buffer, Figure 2a, stability is preserved by adding a phase-lead network,  $R_C$  and  $C_C$ . Voltage drop across  $R_C$  will reduce output voltage swing with heavy loads. An alternate circuit, Figure 2b, does not limit the output with low load impedance. It provides a small amount of positive feedback to reduce the net feedback factor. Input impedance of this circuit falls at high frequency as op amp gain rolloff reduces the bootstrap action on the compensation network.

Figures 2c and 2d show compensation techniques for noninverting amplifiers. Like the follower circuits, the circuit in Figure 2d eliminates voltage drop due to load current, but at the penalty of somewhat reduced input impedance at high frequency.

Figures 2e and 2f show input lead compensation networks for inverting and difference amplifier configurations.

## NOISE PERFORMANCE

Op amp noise is described by two parameters—noise voltage and noise current. The voltage noise determines the noise performance with low source impedance. Low noise bipolar-input op amps such as the OPA27 and OPA37 provide very low voltage noise. But if source impedance is greater than a few thousand ohms, the current noise of bipolar-input op amps react with the source impedance and will dominate. At a few thousand ohms source impedance and above, the OPA2604 will generally provide lower noise.

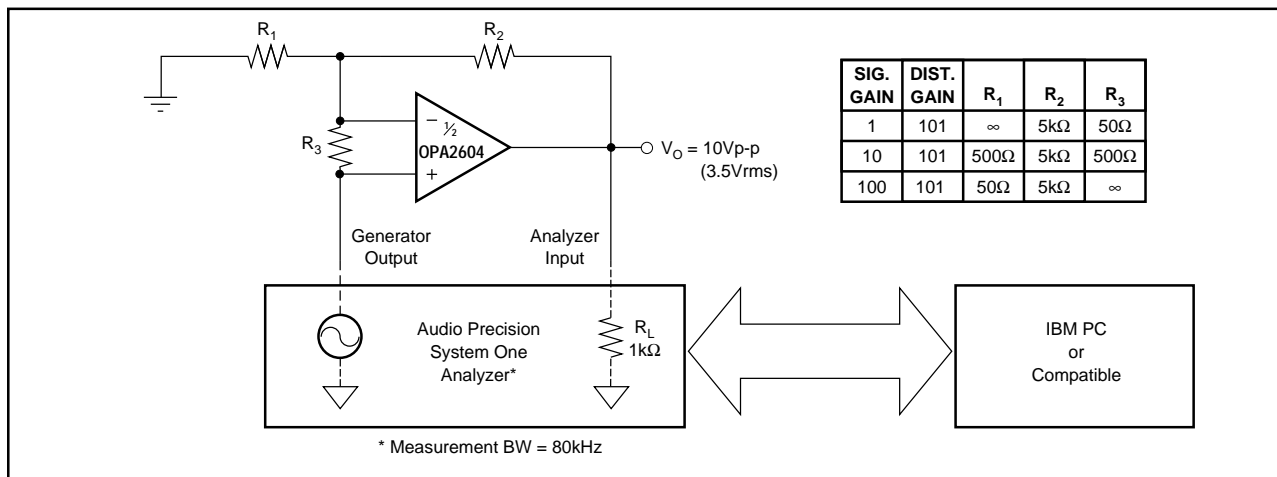
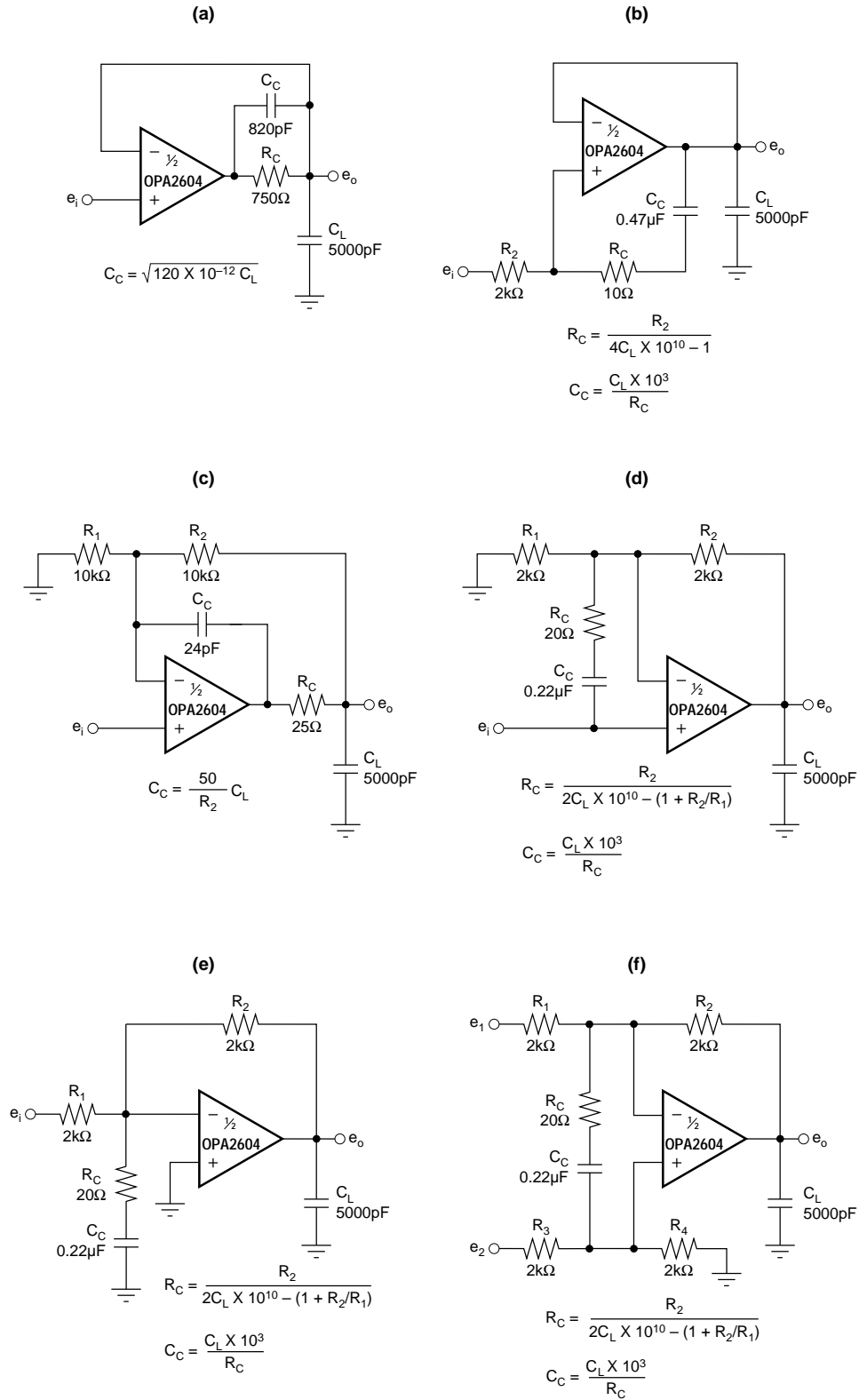


FIGURE 1. Distortion Test Circuit.





NOTE: Design equations and component values are approximate. User adjustment is required for optimum performance.

FIGURE 2. Driving Large Capacitive Loads.

## POWER DISSIPATION

The OPA2604 is capable of driving 600Ω loads with power supply voltages up to ±24V. Internal power dissipation is increased when operating at high power supply voltage. The typical performance curve, Power Dissipation vs Power Supply Voltage, shows quiescent dissipation (no signal or no load) as well as dissipation with a worst case continuous sine wave. Continuous high-level music signals typically produce dissipation significantly less than worst case sine waves.

Copper leadframe construction used in the OPA2604 improves heat dissipation compared to conventional plastic packages. To achieve best heat dissipation, solder the device directly to the circuit board and use wide circuit board traces.

## OUTPUT CURRENT LIMIT

Output current is limited by internal circuitry to approximately ±40mA at 25°C. The limit current decreases with increasing temperature as shown in the typical curves.

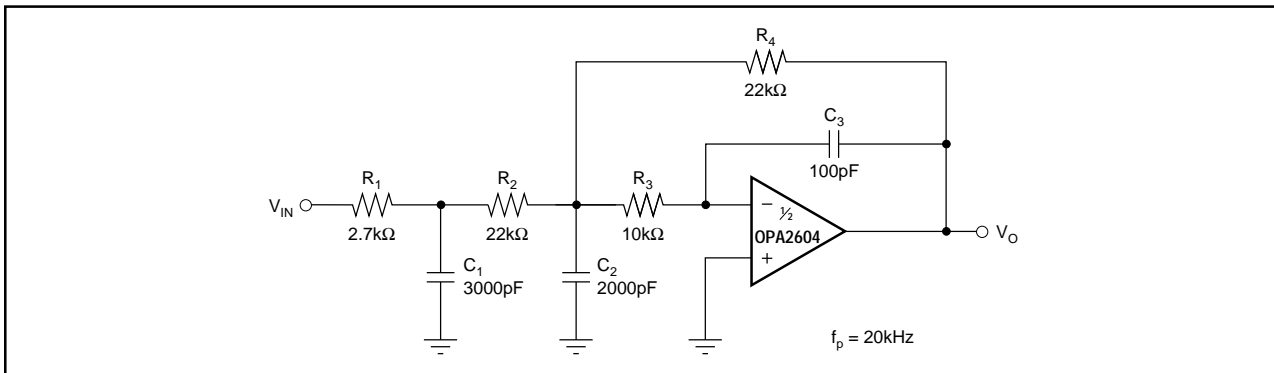


FIGURE 3. Three-Pole Low-Pass Filter.

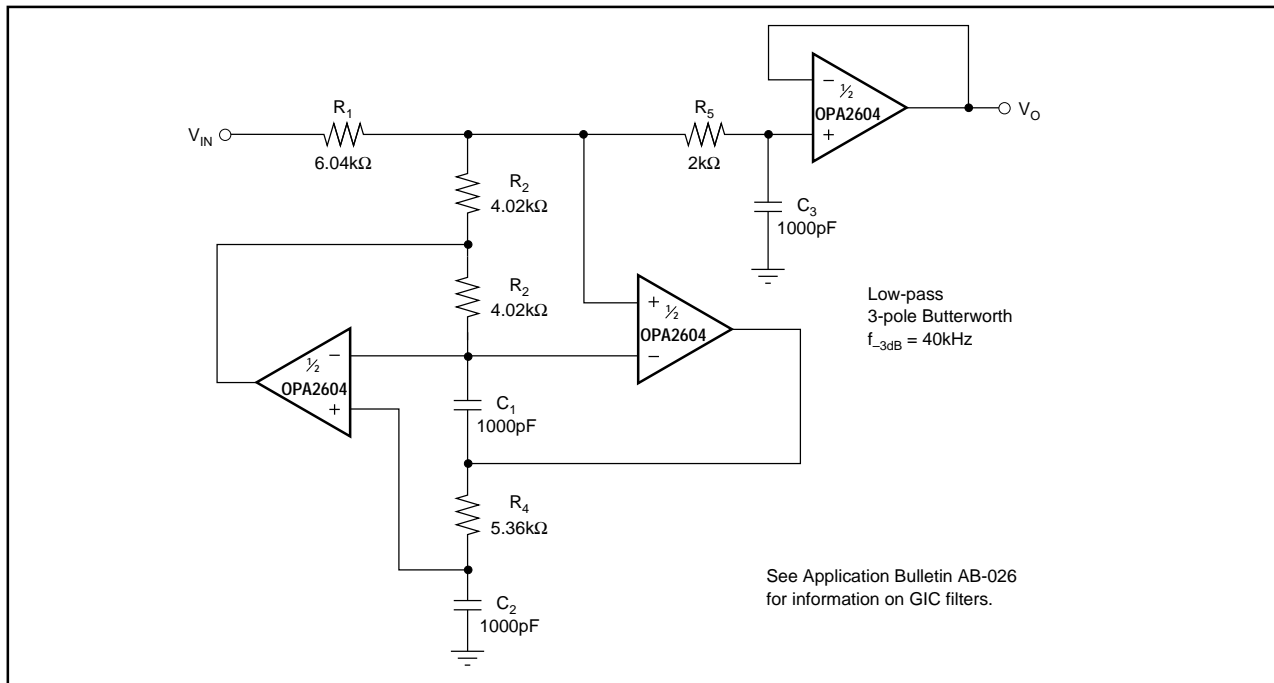


FIGURE 4. Three-Pole Generalized Immittance Converter (GIC) Low-Pass Filter.

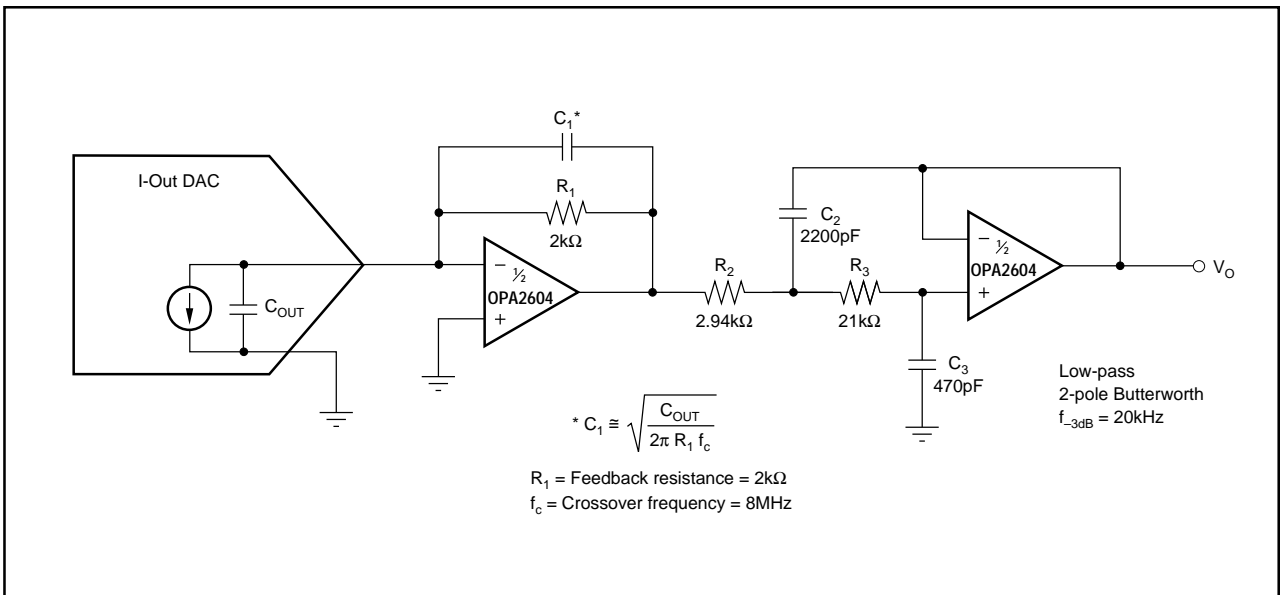


FIGURE 5. DAC I/V Amplifier and Low-Pass Filter.

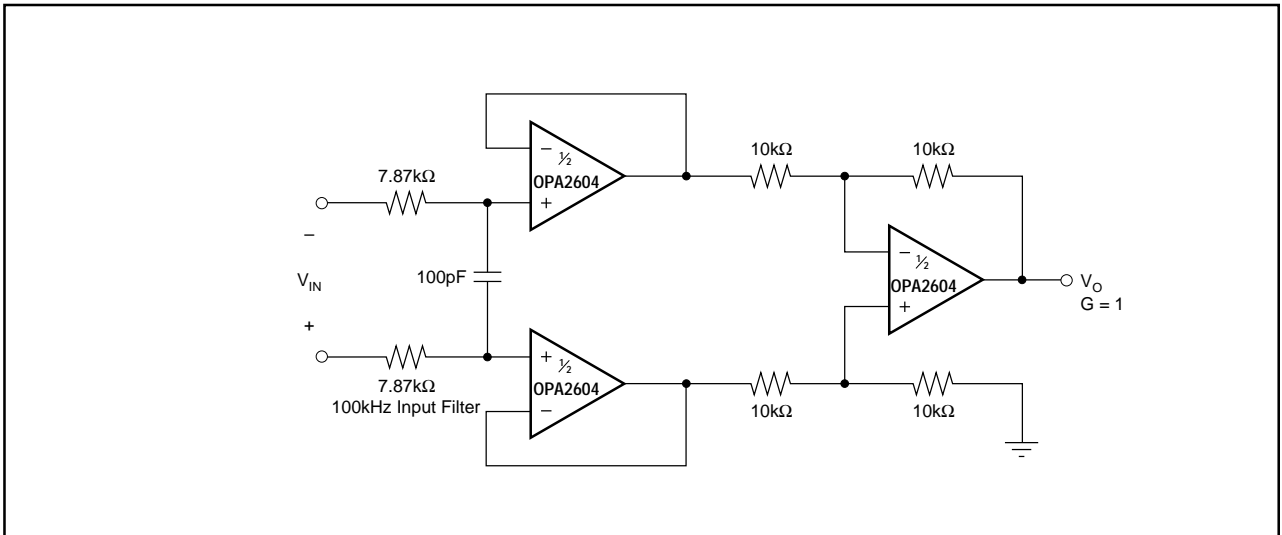


FIGURE 6. Differential Amplifier with Low-Pass Filter.

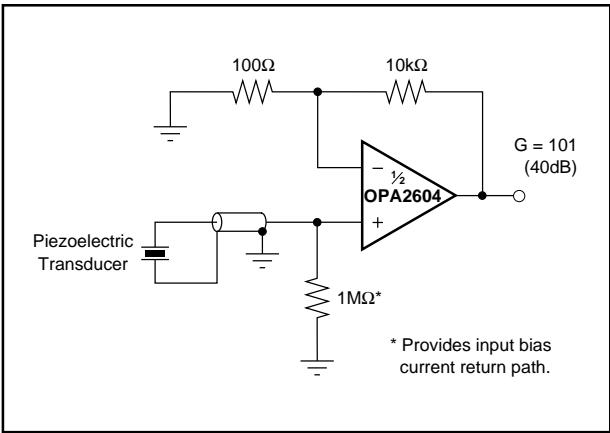


FIGURE 7. High Impedance Amplifier.

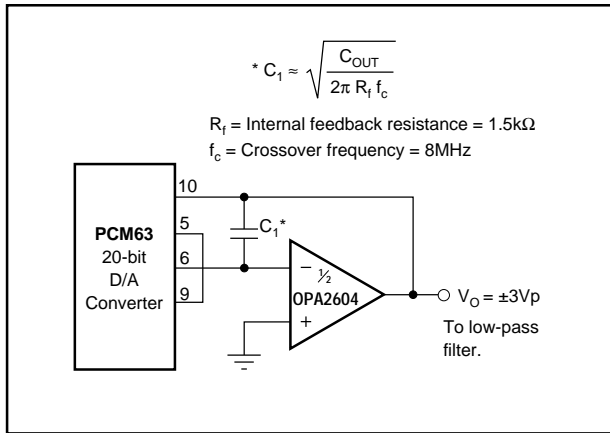


FIGURE 8. Digital Audio DAC I-V Amplifier.

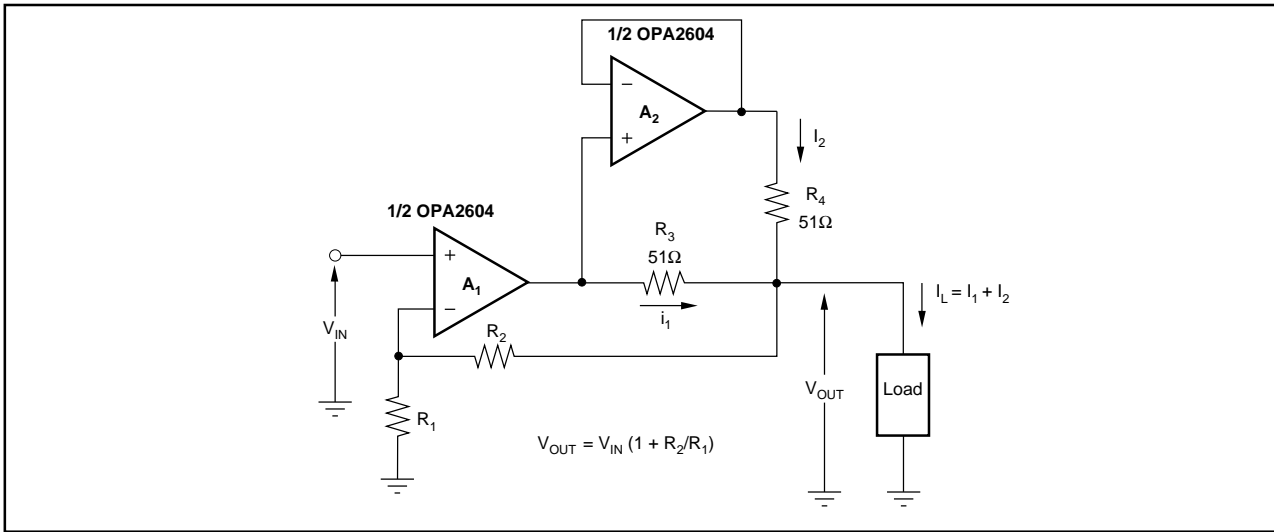


FIGURE 9. Using the Dual OPA2604 Op Amp to Double the Output Current to a Load.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
OPA2604AP	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2604APG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2604AU	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2604AU/2K5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA2604AU/2K5E4	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
OPA2604AUE4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2604AUG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
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